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USE PDS360

MBRM360

3A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

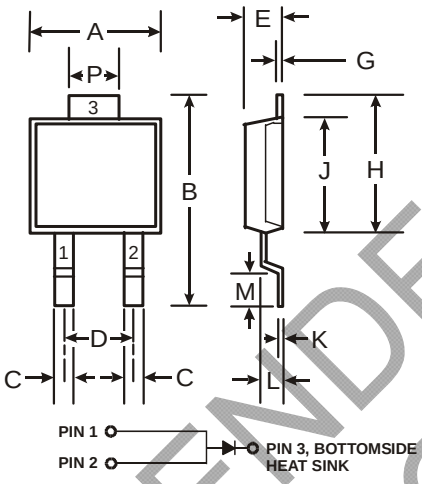
POWERMITE®3

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Reverse Current
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- **Lead Free Finish/RoHS Compliant Version (Note 2)**

Mechanical Data

- Case: POWERMITE®3
- Case Material: Molded Plastic: UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish). e3
- Polarity: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.072 grams (approximate)



Note: Pins 1 & 2 must be electrically connected at the printed circuit board.

POWERMITE®3		
Dim	**Min**	**Max**
A	4.03	4.09
B	6.40	6.61
C	.889 NOM	
D	1.83 NOM	
E	1.10	1.14
G	.178 NOM	
H	5.01	5.17
J	4.37	4.43
K	.178 NOM	
L	.71	.77
M	.36	.46
P	1.73	1.83
All Dimensions in mm		

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	60	V
RMS Reverse Voltage	$V_{R(RMS)}$	42	V
Average Rectified Output Current (See also Figure 5)	I_O	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load @ T_C = 25°C @ T_C = 100°C	I_{FSM}	100 50	A
Typical Thermal Resistance Junction to Soldering Point	$R_{\theta JS}$	3.2	°C/W
Operating Temperature Range	T_j	-55 to +125	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	60	—	—	V	I_R = 0.2mA
Forward Voltage	V_{FM}	— — — —	0.59 0.53 0.72 0.63	0.63 0.57 0.76 0.67	V	I_F = 3A, T_j = 25°C I_F = 3A, T_j = 125°C I_F = 6A, T_j = 25°C I_F = 6A, T_j = 125°C
Reverse Current (Note 1)	I_{RM}	— — —	2.0 0.6 2.5	200 20 150	µA mA mA	T_j = 25°C, V_R = 60V T_j = 100°C, V_R = 60V T_j = 125°C, V_R = 60V
Total Capacitance	C_T	—	130	—	pF	f = 1.0MHz, V_R = 4.0V DC

Notes: 1. Short duration pulse test used to minimize self-heating effect.
2. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.

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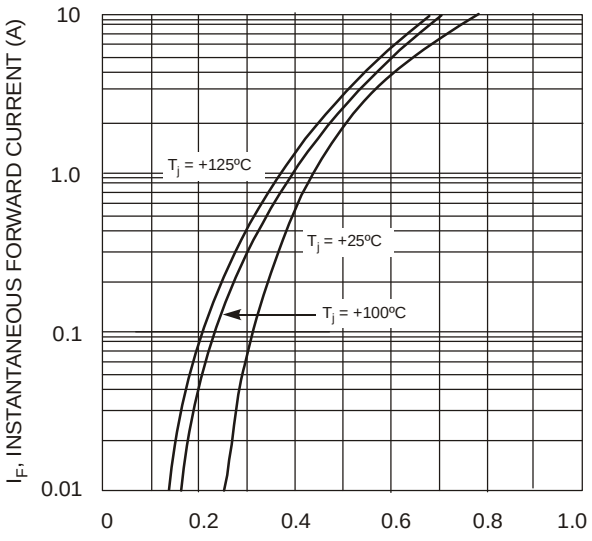


Fig. 1 Typical Forward Characteristics

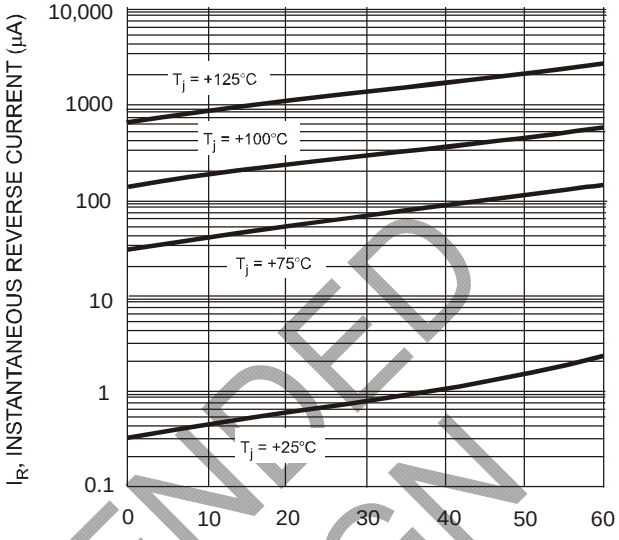


Fig. 2 Typical Reverse Characteristics

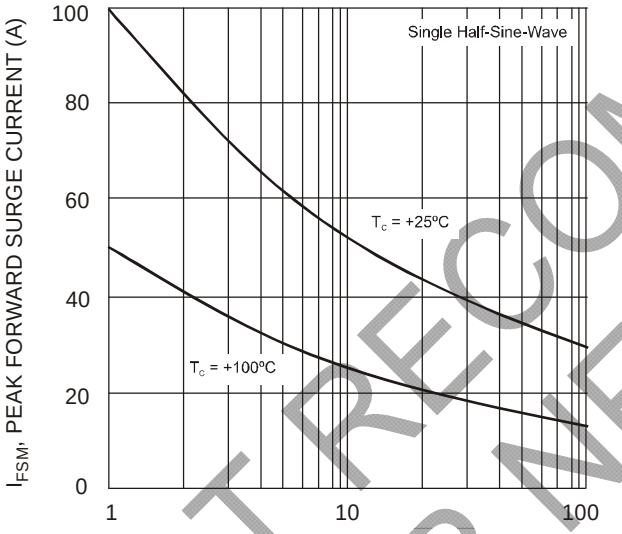


Fig. 3 Max Non-Repetitive Peak Forward Surge Current

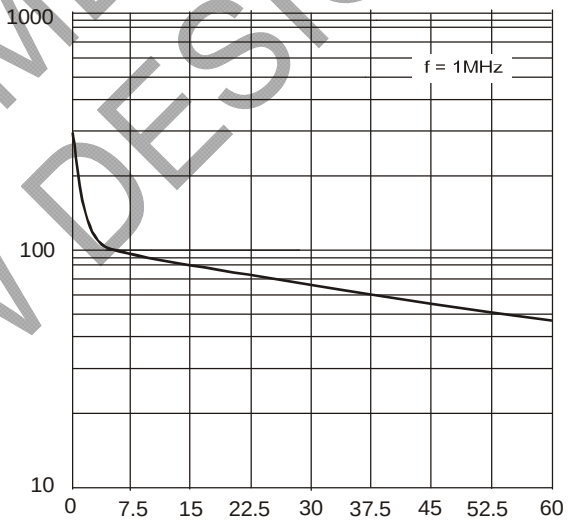


Fig. 4 Typical Capacitance vs. Reverse Voltage

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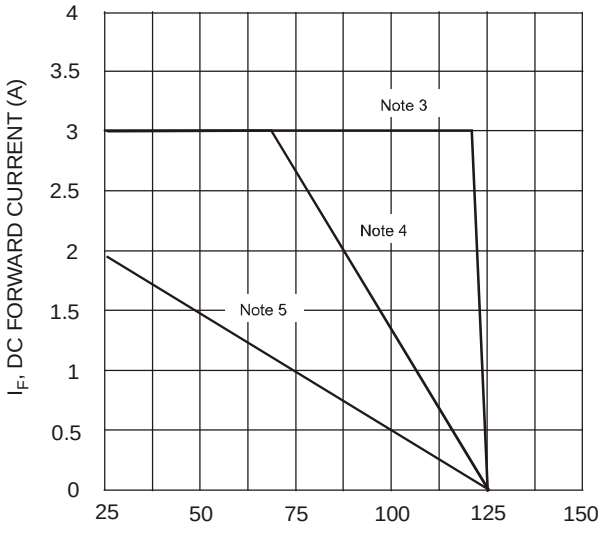


Fig. 5 DC Forward Current Derating

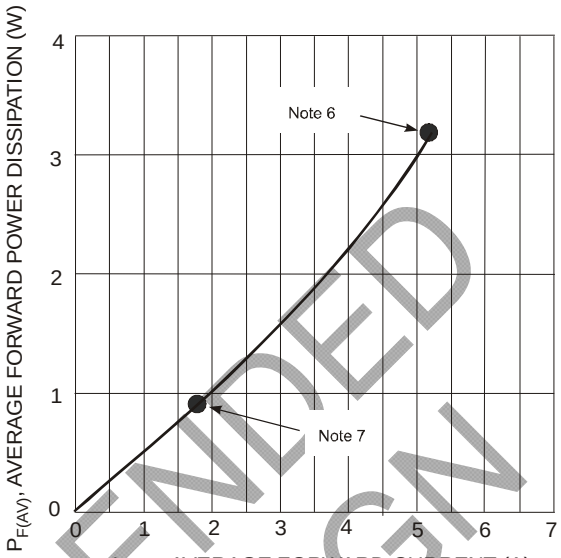


Fig. 6 Forward Power Dissipation

Notes:
3. $T_A = T_{SOLDERING\ POINT}$, $R_{\theta JS}$ = 3.2°C/W, $R_{\theta SA}$ = 0°C/W.
4. Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". $R_{\theta JA}$ in range of 20-40°C/W.
5. Device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. $R_{\theta JA}$ in range of 100-120°C/W.
6. Maximum power dissipation when the device is mounted in accordance to the conditions described in Note 4.
7. Maximum power dissipation when the device is mounted in accordance to the conditions described in Note 5.

Ordering Information (Note 8)

Device	Packaging	Shipping
MBRM360-13-F	POWERMITE®3	5000/Tape & Reel

Notes: 8. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



MBRM360 = Product type marking code
Ↄ¦¦ = Manufacturers' code marking
YYWW = Date code marking
YY = Last digit of year (ex: 02 for 2002)
WW = Week code (01 to 53)
(K) = Factory Designator

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